



SANYO Semiconductors

# DATA SHEET

An ON Semiconductor Company

## LC749403BG — CMOS IC Silicon gate LCD Picture Quality Improvement IC

### Overview

LC749403BG is a IC which enables higher picture quality in LCD products by improving the signals outputed to the LCD panel. In addition to the function to improve the picture quality of the color equation and the brightness correction, smooth picture quality is realized by converting One Seg video from 15fps to 30fps using frame interpolation technique.

It supports up to WVGA resolution. \*

### Features

#### (1) Digital Input/Output

- Supports digital video input: YCbCr/YPbPr 24bit,16bit (4: 2: 2) signals or ITU-R BT.656 (8bit) input
- Digital RGB 24 bit signal input
- Digital RGB 18bit/24bit signal output
- Digital YCbCr 16bit/24bit signal output

#### (2) Picture Quality Improvement Function

- Y signal picture quality improvement: brightness adjustment, contour correction,CDEX (Color Depth Expander),
- C signal picture quality improvement: color exciter,skin color correction,color and hue adjustment
- RGB signal picture quality improvement: brightness, contrast, white balance, black balance, gamma correction

#### (3) Panel Interface

- Embedded timing controller for panel driver
- Automatic timing signal generation for panel protection
- PWM for backlight control (video adaptation low power consumption processing)

#### (4) Frame interpolation (×2) for One-Seg broadcast

- Double-speed (×2) mode (15fps ⇒ 30fps)  
Intermediate image is predicted from the previous and next image.

\*: Video input of the LC749403BG meets the following conditions:

- (1) horizontal resolution is under 880 dots, and (2) vertical resolution is under 480 lines.

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**LSI Specifications**

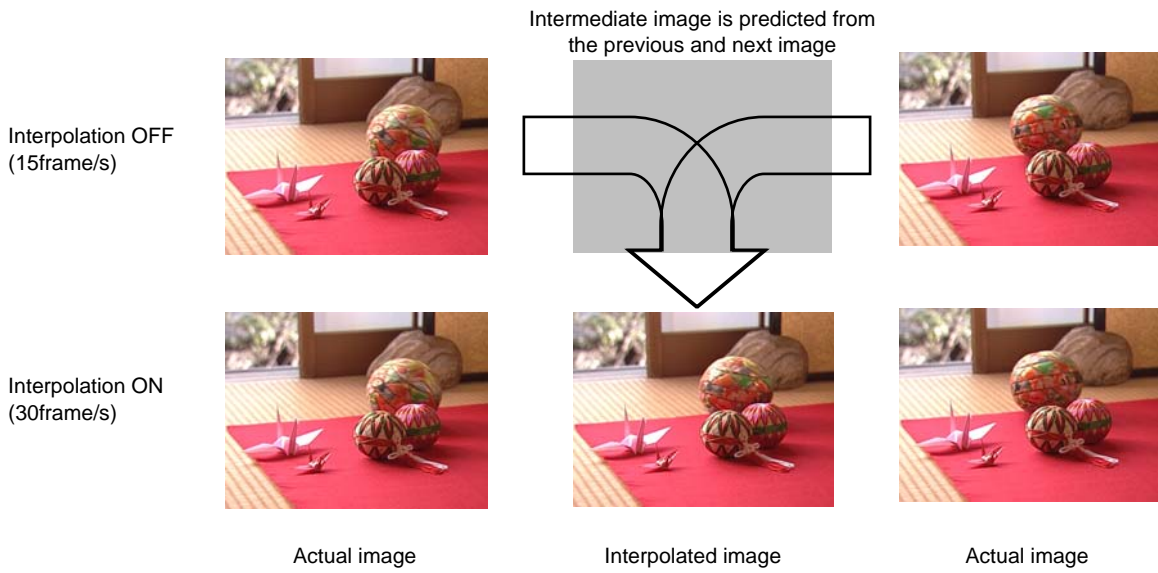
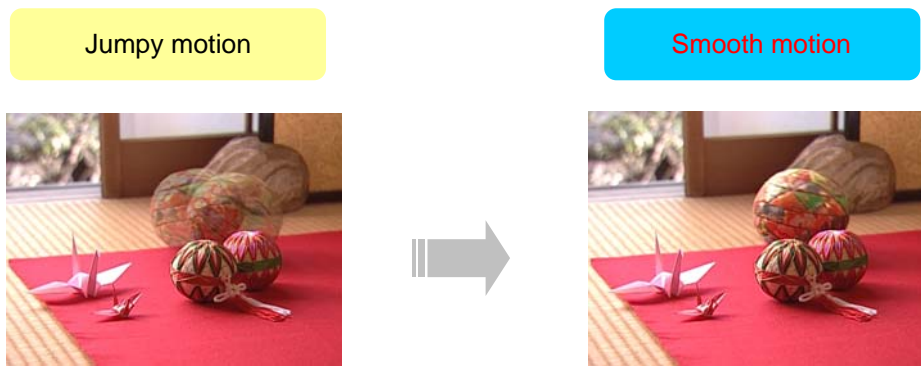
- Power supply voltage (typ)
  - Core block: 1.2V
  - SDRAM I/F block: 1.8V
  - I/O block: 1.8V/2.85V/3.3V selectable
- Maximum operating frequency
  - internal: 36MHz
  - SDRAM I/F block: 80MHz
- Package: FBGA144 11mm × 11mm (stacked MCP with SDRAM)

**Target Application**

- LCD display devices, One-Seg broadcast receiver (Car-Navigation, One-Seg TV, Portable DVD player, etc)

**Frame interpolation (×2) example**

Smooth image quality is realized by converting One Seg video from 15fps to 30fps using frame interpolation technique



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## CDEX (Color Depth Expander) Example

This specification may be changed without any notices for product improvement.



## Specifications

**Absolute Maximum Ratings** at  $T_a = 25^\circ\text{C}$ ,  $DV_{SS} = 0\text{V}$ ,  $AV_{SS\_PLL} = 0\text{V}$ ,  $AV_{SS\_OSC} = 0\text{V}$ ,  $SDV_{SS} = 0\text{V}$ ,  $SDV_{SSQ} = 0\text{V}$

Parameter	Symbol	Conditions	Ratings	unit
Maximum supply voltage (I/O)	$DV_{DD\_IO}$		-0.3 to +3.96	V
Maximum supply voltage (SDRAM, SDRAMIF I/O, PLL)	$DV_{DD\_SDIO}$ , $AV_{DD\_PLL}$ , $SDV_{DD}$ , $SDV_{DDQ}$		-0.3 to +2.6	V
Maximum supply voltage (core, osc)	$DV_{DD\_CORE}$ $AV_{DD\_OSC}$		-0.3 to +1.8	V
Digital input voltage	$V_I$		-0.3 to $DV_{DD\_IO}+0.3$	V
Digital output voltage	$V_O$		-0.3 to $DV_{DD\_IO}+0.3$	V
Operating temperature	$T_{opr}$		-40 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$		-55 to +125	$^\circ\text{C}$

**Allowable Operation Ranges** at  $T_a = -40$  to  $+85^\circ\text{C}$ ,  $DV_{SS} = 0\text{V}$ ,  $AV_{SS\_PLL} = 0\text{V}$ ,  $AV_{SS\_OSC} = 0\text{V}$ ,  $SDV_{SS} = 0\text{V}$ ,  $SDV_{SSQ} = 0\text{V}$

Parameter	Symbol	Conditions	Ratings			unit
			min	typ	max	
Supply voltage (I/O)	$DV_{DD\_IO}$		2.6	2.85	3.6	V
			1.7	1.8	1.95	V
Supply voltage (SDRAMIF I/O)	$DV_{DD\_SDIO}$		1.7	1.8	1.95	V
Supply voltage (SDRAM, PLL)	$SDV_{DD}$ , $SDV_{DDQ}$ $AV_{DD\_PLL}$		1.7	1.8	1.95	V
Supply voltage (core, osc)	$DV_{DD\_CORE}$ $AV_{DD\_OSC}$		1.14	1.2	1.26	V
Input voltage range	$V_{IN}$		0		$DV_{DD\_IO}$	V

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**DC Characteristics** at  $T_a = -40$  to  $+85^\circ\text{C}$ ,  $DV_{SS} = 0\text{V}$ ,  $AV_{SS\_PLL} = 0\text{V}$ ,  $AV_{SS\_OSC} = 0\text{V}$ ,  $SDV_{SS} = 0\text{V}$ ,  
 $SDV_{SSQ} = 0\text{V}$ ,  $DV_{DD\_IO} = 1.7$  to  $3.6\text{V}$ ,  $DV_{DD\_SDIO} = 1.7$  to  $1.95\text{V}$ ,  
 $DV_{DD\_CORE} = 1.14$  to  $1.26\text{V}$ ,  $SDV_{DD} = 1.7$  to  $1.95\text{V}$ ,  $SDV_{DDQ} = 1.7$  to  $1.95\text{V}$

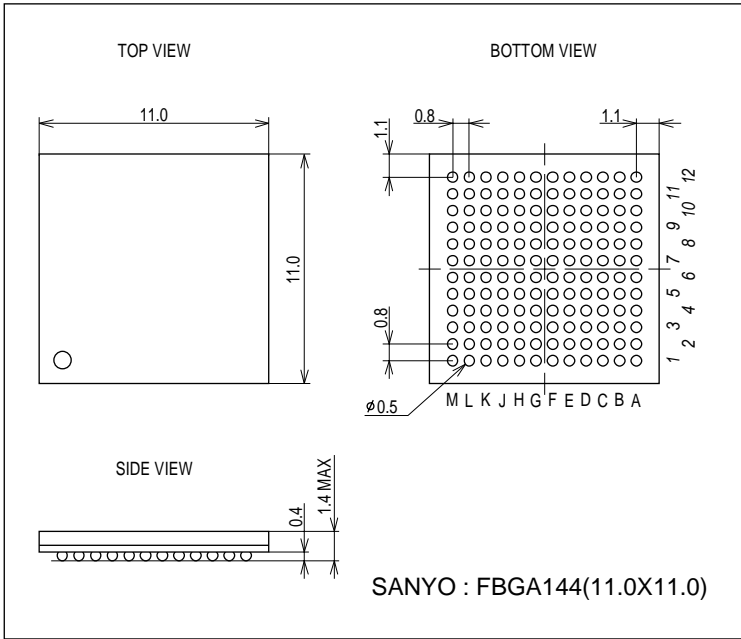
Parameter	Symbol	Conditions	Ratings			unit
			min	typ	max	
Input high-level voltage	$V_{IH}$	CMOS level inputs	$0.7DV_{DD\_IO}$			V
		CMOS level schmitt inputs	$0.7DV_{DD\_IO}$			V
Input low-level voltage	$V_{IL}$	CMOS level inputs			$0.3DV_{DD\_IO}$	V
		CMOS level schmitt inputs			$0.3DV_{DD\_IO}$	V
Input high-level current	$I_{IH}$	$V_I = DV_{DD\_IO}$			10	$\mu\text{A}$
		$V_I = DV_{DD\_IO}$ , with pull-down resistor			100	$\mu\text{A}$
Input low-level current	$I_{IL}$	$V_I = DV_{SS}$	-10			$\mu\text{A}$
Output high-level voltage	$V_{OH}$	CMOS voltage: 2.6V to 3.6V, 1.7V to 1.9V I/O type D: $I_{OH} = -1\text{mA}$ I/O type E: $I_{OH} = -1\text{mA}$ (2mA mode) $I_{OH} = -2\text{mA}$ (4mA mode) I/O type F: $I_{OH} = -2\text{mA}$ (4mA mode) $I_{OH} = -4\text{mA}$ (8mA mode) I/O type G: $I_{OH} = -2\text{mA}$ I/O type H: $I_{OH} = -1\text{mA}$ (2mA mode) $I_{OH} = -2\text{mA}$ (4mA mode)	$DV_{DD\_IO} - 0.4$			V
Output low-level voltage	$V_{OL}$	CMOS			0.4	V
Output leakage current	$I_{OZ}$	In high-impedance output mode			3	$\mu\text{A}$
Pull-down resistance	RDN	condition : typ $T_a = 25^\circ\text{C}$ $DV_{DD\_IO} = 2.85\text{V}$ $DV_{DD\_CORE} = 1.2\text{V}$		98		$\text{k}\Omega$
		condition : typ $T_a = 25^\circ\text{C}$ $DV_{DD\_IO} = 1.8\text{V}$ $DV_{DD\_CORE} = 1.2\text{V}$		69		$\text{k}\Omega$
Operating current drain	$I_{DDOP}$	condition : typ $T_a = 25^\circ\text{C}$ $DV_{DD\_IO} = 2.85\text{V}$ $DV_{DD\_CORE} = 1.2\text{V}$ QVGA, tck = 6.6MHz 10step		25		mA
		condition : typ $T_a = 25^\circ\text{C}$ $DV_{DD\_IO} = 2.85\text{V}$ $DV_{DD\_CORE} = 1.2\text{V}$ WVGA, tck = 34.24MHz 10step		112		mA
Static current drain *1	$I_{DDST}$	condition : typ $T_a = 25^\circ\text{C}$ $DV_{DD\_IO} = 2.85\text{V}$ $DV_{DD\_CORE} = 1.2\text{V}$ Output open, $V_I = DV_{SS}$ or $DV_{DD\_IO}$		35		$\mu\text{A}$

\*1: Certain input pins have build-in pull-down resistors. Thus there are cases where, due to the circuit structure, the static current drain can not be guaranteed.

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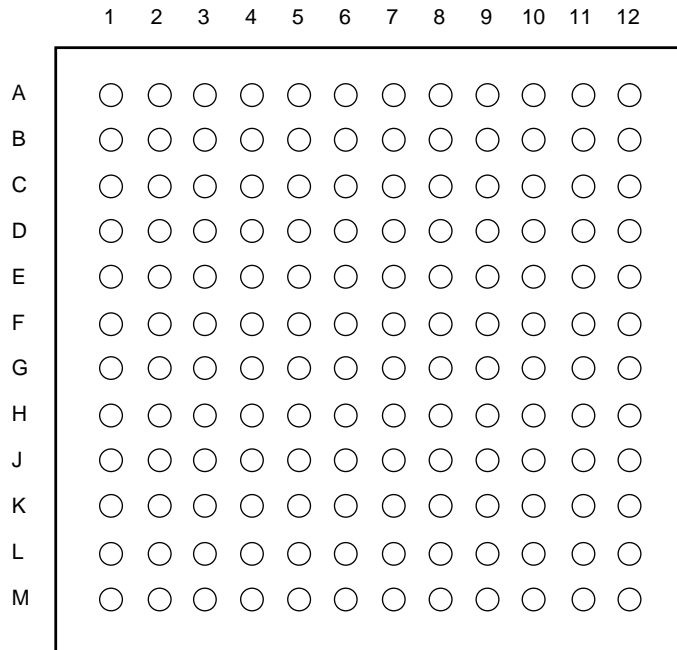
## Package Dimensions

unit : mm (typ)  
3409



## Pin Assignment

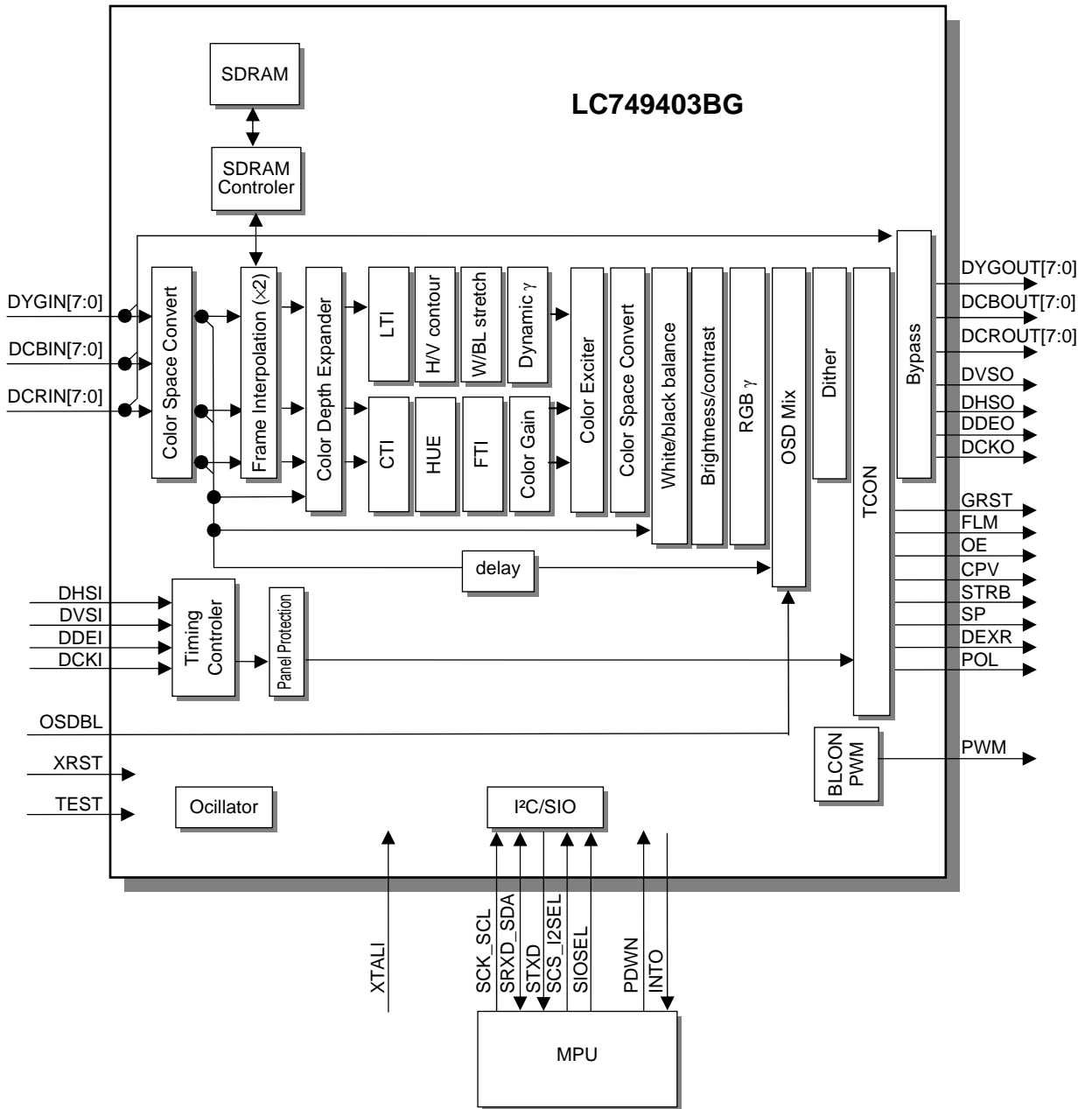
### LC749403BG



Top View

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## Block Diagram



# LC749403BG

## Pin Functions

Pin No.	Pin symbol	I/O Format		Connecting destination		Remarks
		I/O	Format			
A1	AV <sub>DD</sub> _OSC	P	-	Core voltage	Analog	
A2	RC_BIAS	I	J	Resistor	Analog	Bias resistor connection (connect this pin to GND with a 20kΩ)
A3	AV <sub>SS</sub> _OSC	P	-	GND	Analog	
A4	DHSI	I	C	CMOS	Digital	Horizontal synchronizing signal.
A5	DDEI	I	C	CMOS	Digital	Data enable signal. Connect this pin to GND in the internal generation mode.
A6	STXD	O	D	CMOS	Digital	SIO data
A7	SCK_SCL	I	C	CMOS	Digital	Bus clock (common to SIO and I <sup>2</sup> C)
A8	XTALI	I	C	CMOS	Digital	Panel protection, PWM generation clock Connect this pin to GND when not to be used.
A9	TEST	I	B	CMOS	Digital	Test (Normally, connect this pin to GND)
A10	AV <sub>DD</sub> _PLL	P	-	PLL voltage	Analog	
A11	PDO	O	J		Analog	Test (Normally, connect this pin to GND)
A12	AV <sub>SS</sub> _PLL	P	-	GND	Analog	
B1	DCRIN2	I	C	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
B2	DV <sub>DD</sub> _CORE	P	-	Core voltage	Digital	
B3	DV <sub>SS</sub>	P	-	GND	Digital	
B4	DV <sub>SS</sub>	P	-	GND	Digital	
B5	DVSI	I	C	CMOS	Digital	Vertical synchronizing signal
B6	SRXD_SDA	I/O	G	CMOS	Digital	SIO data input/I <sup>2</sup> C data input/output
B7	XRST	I	A	CMOS	Digital	System reset ("L" reset)
B8	DCKI	I	C	CMOS	Digital	Video clock.
B9	DV <sub>DD</sub> _SDIO	P	-	IO voltage	Digital	
B10	DV <sub>SS</sub>	P	-	GND	Digital	
B11	DV <sub>SS</sub>	P	-	GND	Digital	
B12	DCKO	O	F	CMOS	Digital	Video clock output
C1	DCRIN1	I	C	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
C2	DCRIN0	I	C	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
C3	SDV <sub>SS</sub>	P	-	GND	Digital	SDRAM ground
C4	SDV <sub>SS</sub>	P	-	GND	Digital	SDRAM ground
C5	DV <sub>DD</sub> _CORE	P	-	Core voltage	Digital	
C6	INTO	O	D	CMOS	Digital	Interrupt
C7	PDWN	I	A	CMOS	Digital	"L" power down Connect this pin to GND when not to be used.
C8	SIOSEL	I	C	CMOS	Digital	"L": I <sup>2</sup> C slave, "H": 3 wire SIO
C9	DV <sub>SS</sub>	P	-	GND	Digital	
C10	DV <sub>SS</sub>	P	-	GND	Digital	
C11	DHSO/SP2	O	E	CMOS	Digital	Horizontal synchronizing signal/Start pulse signal for source driver
C12	DVSO/FLM2	O	E	CMOS	Digital	Vertical synchronizing signal/Start pulse signal for gate driver

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Pin No.	Pin symbol	Input/output format		Connecting destination		Remarks
		I/O	Format			
D1	DCRIN3	I	C	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
D2	DCRIN4	I	C	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
D3	DCRIN5	I	C	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
D4	DV <sub>SS</sub>	P	-	GND	Digital	
D5	SDV <sub>SS</sub>	P	-	GND	Digital	SDRAM ground
D6	SDV <sub>SS</sub>	P	-	GND	Digital	SDRAM ground
D7	SDV <sub>DD</sub>	P	-	IO voltage	Digital	SDRAM power
D8	SDV <sub>DD</sub>	P	-	IO voltage	Digital	SDRAM power
D9	PWM	O	D	CMOS	Digital	Pulse width modulation waveform
D10	OSDBL	I	C	CMOS	Digital	Data enable signal for external OSD. (Connect to GND when not used.)
D11	SCS_I2SEL	I	A	CMOS	Digital	SIO chip enable/I <sup>2</sup> C slave select
D12	DDEO	O	E	CMOS	Digital	Data enable signal
E1	DCRIN7	I	C	CMOS	Digital	R/Cr video(MSB). Connect this pin to GND when not to be used.
E2	DCRIN6	I	C	CMOS	Digital	R/Cr video. Connect this pin to GND when not to be used.
E3	DYGIN1	I	C	CMOS	Digital	G/Y/656 video. Connect this pin to GND when not to be used.
E4	DYGIN0	I	C	CMOS	Digital	G/Y/656 video (LSB). Connect this pin to GND when not to be used.
E5	DV <sub>DD</sub> _IO	P	-	IO voltage	Digital	
E6	DV <sub>DD</sub> _IO	P	-	IO voltage	Digital	
E7	DV <sub>DD</sub> _IO	P	-	IO voltage	Digital	
E8	DV <sub>DD</sub> _CORE	P	-	Core voltage	Digital	
E9	DBOUT4	O	E	CMOS	Digital	B/Cb/C video
E10	DBOUT5	O	E	CMOS	Digital	B/Cb/C video
E11	DBOUT6	O	E	CMOS	Digital	B/Cb/C video
E12	DBOUT7	O	E	CMOS	Digital	B/Cb/C video (MSB)
F1	DYGIN3	I	C	CMOS	Digital	G/Y/656 video. Connect this pin to GND when not to be used.
F2	DYGIN2	I	C	CMOS	Digital	G/Y/656 video. Connect this pin to GND when not to be used.
F3	DYGIN5	I	C	CMOS	Digital	G/Y/656 video. Connect this pin to GND when not to be used.
F4	DYGIN4	I	C	CMOS	Digital	G/Y/656 video. Connect this pin to GND when not to be used.
F5	DV <sub>DD</sub> _CORE	P	-	Core voltage	Digital	
F6	DV <sub>DD</sub> _CORE	P	-	Core voltage	Digital	
F7	DV <sub>DD</sub> _IO	P	-	IO voltage	Digital	
F8	DV <sub>DD</sub> _CORE	P	-	Core voltage	Digital	
F9	DBOUT1	O	E	CMOS	Digital	B/Cb/C video
F10	DBOUT3	O	E	CMOS	Digital	B/Cb/C video
F11	DBOUT0	O	E	CMOS	Digital	B/Cb/C video (LSB)
F12	DBOUT2	O	E	CMOS	Digital	B/Cb/C video

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Pin No.	Pin symbol	Input/output format		Connecting destination		Remarks
		I/O	Format			
G1	DCBIN0	I	C	CMOS	Digital	B/Cb/C video
G2	DYGIN6	I	C	CMOS	Digital	G/Y/656 video
G3	DYGIN7	I	C	CMOS	Digital	G/Y/656 video
G4	DCBIN1	I	C	CMOS	Digital	B/Cb/C video. Connect this pin to GND when not to be used.
G5	DV <sub>DD</sub> _CORE	P	-	Core Voltage	Digital	
G6	DV <sub>DD</sub> _CORE	P	-	Core Voltage	Digital	
G7	DV <sub>DD</sub> _SDIO	P	-	IO voltage	Digital	
G8	DV <sub>DD</sub> _SDIO	P	-	IO voltage	Digital	
G9	DGOUT5	O	E	CMOS	Digital	G/Y/656 video
G10	DGOUT6	O	E	CMOS	Digital	G/Y/656 video
G11	DGOUT3	O	E	CMOS	Digital	G/Y/656 video
G12	DGOUT7	O	E	CMOS	Digital	G/Y/656 video (MSB)
H1	DCBIN4	I	C	CMOS	Digital	B/Cb/C video
H2	DCBIN3	I	C	CMOS	Digital	B/Cb/C video
H3	DCBIN2	I	C	CMOS	Digital	B/Cb/C video
H4	DCBIN5	I	C	CMOS	Digital	B/Cb/C video
H5	DV <sub>DD</sub> _SDIO	P	-	IO voltage	Digital	
H6	DV <sub>DD</sub> _SDIO	P	-	IO voltage	Digital	
H7	DV <sub>DD</sub> _SDIO	P	-	IO voltage	Digital	
H8	DV <sub>DD</sub> _SDIO	P	-	IO voltage	Digital	
H9	DGOUT0	O	E	CMOS	Digital	G/Y/656 video (LSB)
H10	DGOUT1	O	E	CMOS	Digital	G/Y/656 video
H11	DGOUT2	O	E	CMOS	Digital	G/Y/656 video
H12	DGOUT4	O	E	CMOS	Digital	G/Y/656 video
J1	CPV	I/O	H	CMOS	Digital	Clock signal for gate driver
J2	STRB	I/O	H	CMOS	Digital	Data strobe signal for source driver
J3	DEXR	O	E	CMOS	Digital	Video inverse signal output for DTR
J4	DV <sub>SS</sub>	P	-	GND	Digital	
J5	DV <sub>SS</sub>	P	-	GND	Digital	
J6	DV <sub>SS</sub>	P	-	GND	Digital	
J7	DV <sub>SS</sub>	P	-	GND	Digital	
J8	DV <sub>SS</sub>	P	-	GND	Digital	
J9	DV <sub>SS</sub>	P	-	GND	Digital	
J10	DV <sub>SS</sub>	P	-	GND	Digital	
J11	DV <sub>SS</sub>	P	-	GND	Digital	
J12	DROUT7	I/O	H	CMOS	Digital	R/Cr video (MSB)

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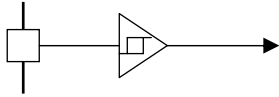
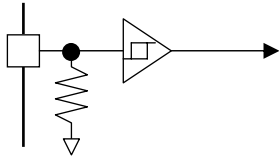
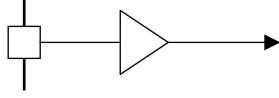
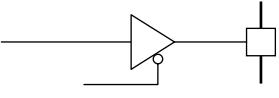
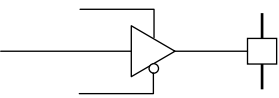
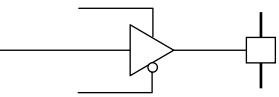
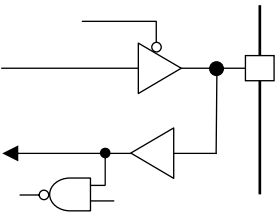
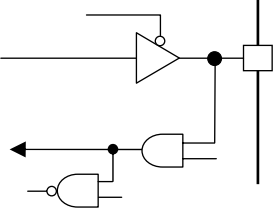
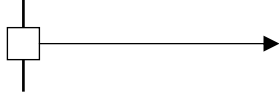
Pin No.	Pin symbol	Input/output format		Connecting destination		Remarks
		I/O	Format			
K1	FLM	I/O	H	CMOS	Digital	Start pulse signal for gate driver
K2	OE	I/O	H	CMOS	Digital	Output enable signal for gate driver
K3	DV <sub>SS</sub>	P	-	GND	Digital	
K4	DV <sub>SS</sub>	P	-	GND	Digital	
K5	DV <sub>SS</sub>	P	-	GND	Digital	
K6	DV <sub>SS</sub>	P	-	GND	Digital	
K7	DV <sub>SS</sub>	P	-	GND	Digital	
K8	DV <sub>SS</sub>	P	-	GND	Digital	
K9	DV <sub>SS</sub>	P	-	GND	Digital	
K10	DV <sub>SS</sub>	P	-	GND	Digital	
K11	DROUT0	I/O	H	CMOS	Digital	R/Cr video (LSB)
K12	DROUT6	I/O	H	CMOS	Digital	R/Cr video
L1	DCBIN7	I	C	CMOS	Digital	B/Cb/C video (MSB). Connect this pin to GND when not to be used.
L2	SP	I/O	H	CMOS	Digital	Start pulse signal for source driver
L3	SDV <sub>DDQ</sub>	P	-	IO voltage	Digital	SDRAM power *1
L4	SDV <sub>DDQ</sub>	P	-	IO voltage	Digital	SDRAM power *1
L5	SDV <sub>DDQ</sub>	P	-	IO voltage	Digital	SDRAM power *1
L6	SDV <sub>DDQ</sub>	P	-	IO voltage	Digital	SDRAM power *1
L7	SDV <sub>DDQ</sub>	P	-	IO voltage	Digital	SDRAM power *1
L8	SDV <sub>DDQ</sub>	P	-	IO voltage	Digital	SDRAM power *1
L9	SDV <sub>DDQ</sub>	P	-	IO voltage	Digital	SDRAM power *1
L10	DV <sub>SS</sub>	P	-	GND	Digital	
L11	DROUT2	I/O	H	CMOS	Digital	R/Cr video
L12	DROUT5	I/O	H	CMOS	Digital	R/Cr video
M1	DCBIN6	I	C	CMOS	Digital	B/Cb/C video. Connect this pin to GND when not to be used.
M2	POL	O	E	CMOS	Digital	Voltage polarity selection signal for source driver
M3	GRST	I/O	H	CMOS	Digital	Reset signal for gate driver
M4	SDV <sub>SSQ</sub>	P	-	GND	Digital	SDRAM ground *2
M5	SDV <sub>SSQ</sub>	P	-	GND	Digital	SDRAM ground *2
M6	SDV <sub>SSQ</sub>	P	-	GND	Digital	SDRAM ground *2
M7	SDV <sub>SSQ</sub>	P	-	GND	Digital	SDRAM ground *2
M8	SDV <sub>SSQ</sub>	P	-	GND	Digital	SDRAM ground *2
M9	SDV <sub>SSQ</sub>	P	-	GND	Digital	SDRAM ground *2
M10	DROUT1	I/O	H	CMOS	Digital	R/Cr video
M11	DROUT3	I/O	H	CMOS	Digital	R/Cr video
M12	DROUT4	I/O	H	CMOS	Digital	R/Cr video

\*1: We recommend isolated power to be supplied to SDRAM for improved noise immunity.

\*2: We recommend isolated ground to be supplied to SDRAM for improved noise immunity.

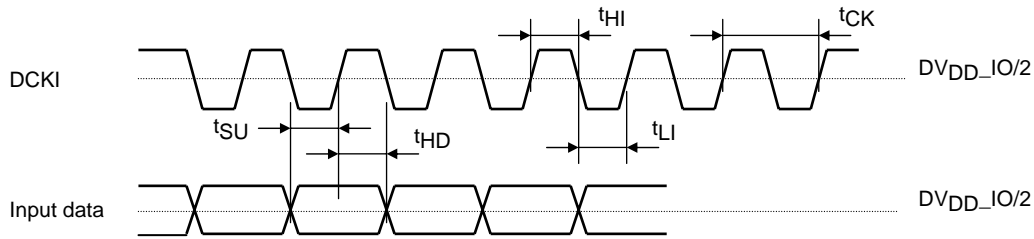
# LC749403BG

## Pin Circuits

In/output form	Function	Equivalent circuit	Application Terminal
A	Schmitt trigger CMOS input		XRST, PDWN, SCS_I2SEL
B	CMOS input with built-in pull-down resistor		TEST
C	CMOS input		SCK_SCL, SIOSEL, DVSI, DSI, DDEI, OSDBL, DYGIN7, DYGIN6, DYGIN5, DYGIN4, DYGIN3, DYGIN2, DYGIN1, DYGIN0, DCBIN7, DCBIN6, DCBIN5, DCBIN4, DCBIN3, DCBIN2, DCBIN1, DCBIN0, DCRIN7, DCRIN6, DCRIN5, DCRIN4, DCRIN3, DCRIN2, DCRIN1, DCRIN0
D	2mA 3-STATE drive CMOS output		STXD, PWM, INTO
E	2mA/4mA switching 3-STATE drive CMOS output		DBOUT7, DBOUT6, DBOUT5, DBOUT4, DBOUT3, DBOUT2, DBOUT1, DBOUT0, DGOUT7, DGOUT6, DGOUT5, DGOUT4, DGOUT3, DGOUT2, DGOUT1, DGOUT0, DHSO/SP2, DVSO/FLM2, DDEO FLM, DEXR, POL
F	4mA/8mA switching 3-STATE drive CMOS output		DCKO
G	4mA 3-STATE drive CMOS input/output		SRXD_SDA
H	2mA/4mA switching 3-STATE CMOS input/output		DROUT7, DROUT6, DROUT5, DROUT4, DROUT3, DROUT2, DROUT1, DROUT0, GRST, CPV, SP, OE, STRB
J	Analog input/output		RC_BIAS

Input/Output Timing

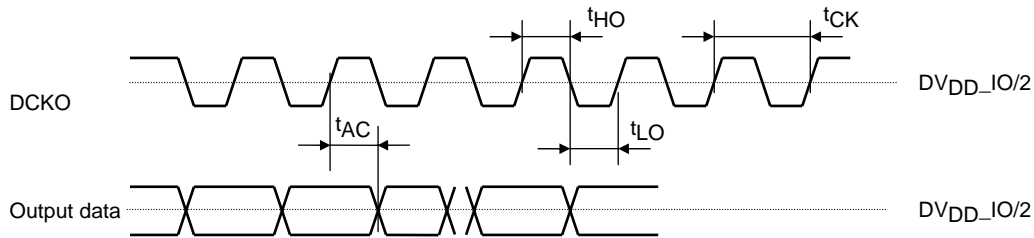
(1) Input data timing



Pin Name	Parameter	Symbol	min	typ	max	unit
DCKI	Clock cycle	$t_{CK}$	25			ns
	Duty			50		%
DCRIN*, DYGIN*, DCBIN*, DVSI, DHSI, DDEI, OSDBL	Input data set up time (DV <sub>DD_IO</sub> =2.6 to 3.6V)	$t_{SU}$	3			ns
	Input data set up time (DV <sub>DD_IO</sub> =1.7 to 1.95V)	$t_{SU}$	3			ns
	Input data hold time (DV <sub>DD_IO</sub> =2.6 to 3.6V)	$t_{HD}$	2			ns
	Input data hold time (DV <sub>DD_IO</sub> =1.7 to 1.95V)	$t_{HD}$	2			ns

\*: We recommend a 50% duty cycle for the input clock.

(2) Output data timing



Pin Name	Parameter	Symbol	min	typ	max	unit
DCKO	Clock cycle	$t_{CK}$	25			ns
	Duty			50		%
DROUT*, DGOUT*, DBOUT*, DVSO, DHSO, DDEO, DEXR, POL, SP, STRB, CPV, OE, FLM, GRST	Output data delay time (DV <sub>DD_IO</sub> =2.6 to 3.6V) I/O typ E: 4mA setting I/O typ F: 8mA setting	$t_{AC}$	-3		3	ns
	Output data delay time (DV <sub>DD_IO</sub> =2.6 to 3.6V) I/O typ E: 2mA setting I/O typ F: 4mA setting	$t_{AC}$	-3		6	ns
	Output data hold time (DV <sub>DD_IO</sub> =1.7 to 1.95V) I/O typ E: 4mA setting I/O typ F: 8mA setting	$t_{AC}$	-5		4	ns
	Output data hold time (DV <sub>DD_IO</sub> =1.7 to 1.95V) I/O typ E: 2mA setting I/O typ F: 4mA setting	$t_{AC}$	-6		9	ns

\*: When DCKO is set to the forward rotation output. Output load capacity: 5pF

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